FABRICATION NOTES:

1) LATEST VERSION OF ALL REFERENCED SPECIFICATIONS TO BE USED UNLESS OTHERWISE SPECIFIED.

2) UNLESS OTHERWISE SPECIFIED ALL IPC SPECIFICATIONS TO BE:
☒ CLASS 2 ☐ CLASS 3

3) FABRICATE IN ACCORDANCE WITH IPC-A-600H UNLESS OTHERWISE SPECIFIED.

4) INSPECT IN ACCORDANCE WITH IPC-6012C UNLESS OTHERWISE SPECIFIED.

5) MATERIAL:
BASE LAMINATE TO MEET THE REQUIREMENTS OF IPC-4101A /24 /26/29/98
COPPER CLAD HIGH TEMPERATURE FR4 CLASS EPOXY GLASS (UL94V-0)
MUST SURVIVE A LEAD FREE ASSEMBLY, MAX REFLOW OF 260° C (6 PASSES)
Tg >= 150° C (MIN) FOR 8 LAYERS OR LESS (REF)
Tg >= 170° C (MIN) FOR > 8 LAYERS (REF)
Td >= 340° C
CTE Z-AXIS EXPANSION (50 DEG. C TO 260 DEG. C) <= 3.5%

6) OVERALL BOARD THICKNESS (+/-10%):
☒ 0.062" ☐ 0.093" ☐ 0.125" ☐ OTHER

7) COPPER WEIGHT:
☐ STARTING ☒ FINISHED
OUTER LAYERS : ☐ SEE STACK-UP ☒ 1/2 oz. ☐ 1 oz. ☐ 2 oz.
INNER LAYERS : ☐ SEE STACK-UP ☒ 1/2 oz. ☐ 1 oz. ☐ 2 oz. ☐ NONE

8) FINISH:
SOLDER MASK OVER BARE COPPER (SMOBC)
☒ ELECTROLESS NICKEL IMMERSION GOLD (ENIG) 2-8 uINCHES GOLD OVER 150-250 uINCHES NICKEL PER IPC-4552.
☐ IMMERSION SILVER 8-14 uINCHES
☐ IMMERSION TIN 25-50 uINCHES
☐ OSP ENTEK OR EQUIVALENT

9) SOLDER MASK:
☒ LIQUID PHOTOIMAGEABLE ☐ DRY FILM ☐ NONE
☒ GREEN ☐ RED ☐ BLUE

10) SILKSCREEN INK NOT TO COVER ANY PORTION OF EXPOSED COPPER. FABRICATOR TO CLIP ANY NON-CONFORMING SILKSCREEN NOMENCLATURE. SILKSCREEN USING EPOXY BASED INK:
☒ BOTH SIDES ☐ PRIMARY SIDE ☐ SECONDARY SIDE ☐ NONE
☒ WHITE ☐ YELLOW ☐ BLACK

11) BOARD EDGE FINGERS:
☐ 30-50 uINCHES HARD GOLD OVER 150-200 uINCHES NICKEL PLATED
☐ BEVELED AND CHAMFERED PER DETAIL ☐ TIN LEAD PLATED
☐ OTHER ☒ NONE

12) CONTROLLED IMPEDANCE:
☐ NONE ☒ SEE STACK-UP DRAWING

13) BARE BOARD ELECTRICAL TEST:
☒ PER SUPPLIED IPC-D-356 NETLIST (REPORT ALL DISCREPANCIES) ☐ NO TEST REQUIRED
☒ BOARD CONTAINS FAN-OUTS ON UNUSED PINS. THE RESULT IS A NET CALLED "NOT_CONNECTED" WHICH LACKS CONTINUITY. THIS IS INTENTIONAL.

14) UL LOGO AND DATE CODE & VENDOR CODE MUST APPEAR IN ETCH ON PRIMARY SIDE, SECONDARY SIDE IS ACCEPTABLE IF THERE IS NO ROOM ON PRIMARY SIDE.

15) TOOLING HOLES MUST BE PRIMARY DRILLED AT THE SAME TIME AS PLATED-THRU HOLES. ALL HOLES MUST BE WITHIN .003" OF RADIAL TRUE POSITION.

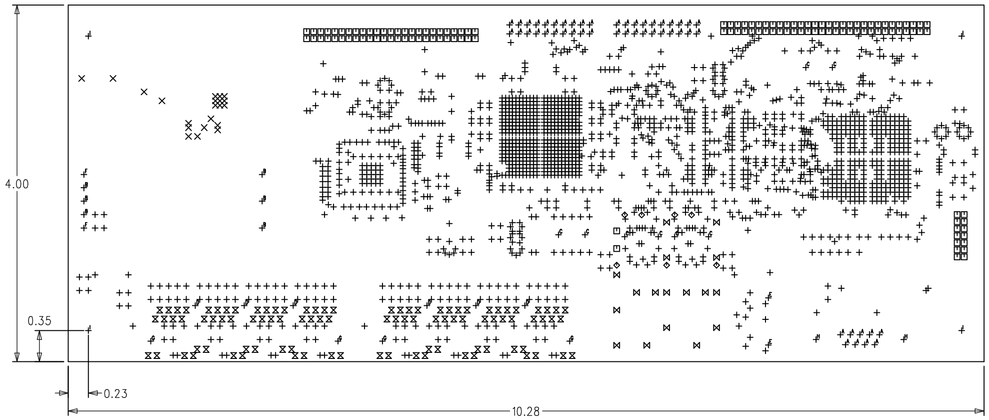
16) PADS MUST BE FINISHED TO WITHIN +/- .0015" OF THE MINOR DIMENSION (PAD WIDTH) & +/- .002" OF THE MAJOR DIMENSION (PAD LENGTH).

17) GLOBAL AND LOCAL FIDUCIALS MUST BE FREE OF ANY MARKINGS.

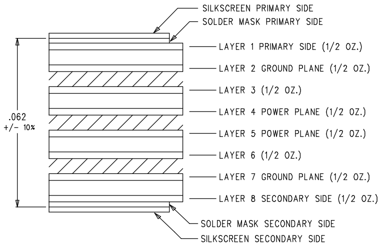
18) REMOVAL OF NON-FUNCTIONAL PADS ON INNER LAYERS ALLOWED.

19) THIEVING OF OUTER LAYERS IS ACCEPTABLE AS LONG AS THE COPPER IS KEPT A MINIMUM OF 0.200" FROM ANY DESIGN FEATURE, UNLESS OTHERWISE SPECIFIED.

20) BOARD TO BE MANUFACTURED IN COMPLIANCE WITH RESTRICTION OF HAZARDOUS SUBSTANCES IN ELECTRONIC AND ELECTRONIC EQUIPMENT (RoHS) DIRECTIVE 2002/95/EC AND WASTE ELECTRICAL AND ELECTRONIC EQUIPMENT (WEEE) DIRECTIVE 2002/96/EC.



SIZE	QTY	SYM	PLATED	TOL
0.012	2006	+	YES	+/-0.003
0.02	21	×	YES	+/-0.003
0.036	126	◻	YES	+/-0.003
0.037	7	◇	NO	+/-0.003
0.038	96	⧗	YES	+/-0.003
0.041	17	⋈	YES	+/-0.003
0.043	49	+A	YES	+/-0.003
0.052	6	+B	YES	+/-0.003
0.062	8	+C	NO	+/-0.003
0.063	6	+D	YES	+/-0.003
0.067	2	+E	NO	+/-0.003
0.072	2	+F	YES	+/-0.003
0.125	4	+G	YES	+/-0.005
0.128	2	+H	YES	+/-0.005
0.154	4	+I	YES	+/-0.005



8 LAYER STACK-UP

CONTROLLED IMPEDANCES:
ALL .0049" TRACES TO BE 90-110 OHMS DIFFERENTIAL.

UNLESS OTHERWISE SPECIFIED
TOLERANCES
.00 ± .010
.000 ± .005
ANGLES ±
APPROVALS
ORIGINATOR DATE
ENG APPD DATE
MFG ENG APPD DATE
CAD APPD DATE

COMPANY NAME

TITLE
FABRICATION DRAWING
BOARD NAME

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SIZE C
NUMBER BOARD NUMBER
SHEET: 1 OF 1
SCALE 1:1
REVISION: REV